Special Issue

Augmented Reality, Virtual Reality, and 3D Reconstruction

Message from the Guest Editors

We are excited to announce the upcoming Special Issue "Augmented Reality, Virtual Reality, and 3D Reconstruction". Emerging AI tools that generate 3D models from text and images, while simplifying object texturing, represent a groundbreaking advancement for Augmented Reality (AR), Virtual Reality (VR), and 3D reconstruction across various scientific fields. Topics of interest for this Special Issue include, but are not limited to:

- AI-generated 3D models
- text-to-3D conversion
- image-based 3D modelling
- object texturing automation
- augmented reality (AR)
- virtual reality (VR)
- 3D reconstruction
- scientific visualization

We warmly invite you to contribute to this Special Issue and share your insights and research on these cutting-edge developments.

Guest Editors

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Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Editor-in-Chief

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